## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
Semiconductor Leading Edge Technologies, Inc.	09/09/2005

#### **RECEIVING PARTY DATA**

Name:	Matsushita Electric Industrial Co., Ltd.	
Street Address:	1006, Oaza Kadoma	
Internal Address:	Kadoma-shi	
City:	Osaka	
State/Country:	JAPAN	
Postal Code:	571-5801	

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	6652212

#### **CORRESPONDENCE DATA**

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NAME OF SUBMITTER:

Anthony Niewyk

Total Attachments: 2

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> PATENT REEL: 016536 FRAME: 0398

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# **ASSIGNMENT**

WHEREAS, Semiconductor Leading Edge Technologies, Inc. a corporation organized and existing under the laws of the Country of Japan, having its principal place of business at 292 Yoshida-cho, Totsuka-ku Yokohama, Kanagawa, JAPAN, holds rights, title and interest in U.S. Patent No. 6,652,212, granted November 25, 2003, entitled:

# CYLINDER, LOAD PORT USING IT, AND PRODUCTION SYSTEM

and WHEREAS, Matsushita Electric Industrial Co., Ltd., a corporation organized and existing under the laws of the Country of Japan, having its principal place of business at 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-5801, JAPAN, wishes to acquire the entire rights, title and interest of said Semiconductor Leading Edge Technologies, Inc. in said U.S. Patent No. 6,652,212;

NOW, THEREFORE, in consideration of the sum of ONE DOLLAR (\$1.00) to us in hand paid, and for other good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, Semiconductor Leading Edge Technologies, Inc. does hereby assign, sell, transfer and set over unto said Matsushita Electric Industrial Co., Ltd., its successors and assigns, its full, entire and exclusive rights, title and interest, for the territory of the United States of America and for all foreign countries, in and to said invention, as described in the application identified above, and in and to said application and any divisions or continuations or continuations-in-part thereof or substitutes therefore which may be filed, and in and to any patents or reissues, renewals or extensions thereof which may be granted on said application or for said invention, and in and to any patent application which may be filed on said invention in countries foreign to the United States of America and any patents granted thereon; said invention, applications, and patents to be held and enjoyed by said Matsushita Electric Industrial Co., Ltd., and its successors or assigns, to the full end of the term or terms for which said patents may be granted, as fully and entirely as the same would have been held by us had this assignment not been made.

We hereby authorize and request the Patent and Trademark Office officials in the United States of America and the Patent Office officials of any and all foreign countries to issue any and all of said patents, when granted to said Matsushita Electric Industrial Co., Ltd., as the assignee of our entire right, title and interest in and to the same for the sole use and enjoyment of said Matsushita Electric Industrial Co., Ltd., its successors and assigns.

PATENT REEL: 016536 FRAME: 0399 Further, we agree to execute all papers and to give such lawful testimony and to perform such other lawful acts as said Matsushita Electric Industrial Co., Ltd., its successors and assigns may require to enable it or them to procure a Letters Patent on said invention or reissues or extensions thereof in the United States of America and/or in any foreign country, and/or to hold, enforce or convey said Letters Patent, reissues or extensions.

Executed this 9th day of September, 2005.

Hiromi Sakurai, Director/General Manager Research Planning Promotion Department Semiconductor Leading Edge Technologies, Inc.

> PATENT REEL: 016536 FRAME: 0400

**RECORDED: 09/15/2005**